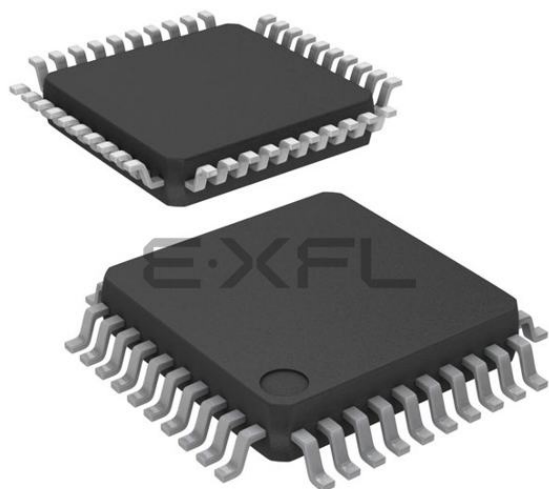




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Details

Product Status	Not For New Designs
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	LED, POR, Voltage Detect, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	32-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21276snfp-x6

1.3 Block Diagram

Figure 1.1 shows a Block Diagram.

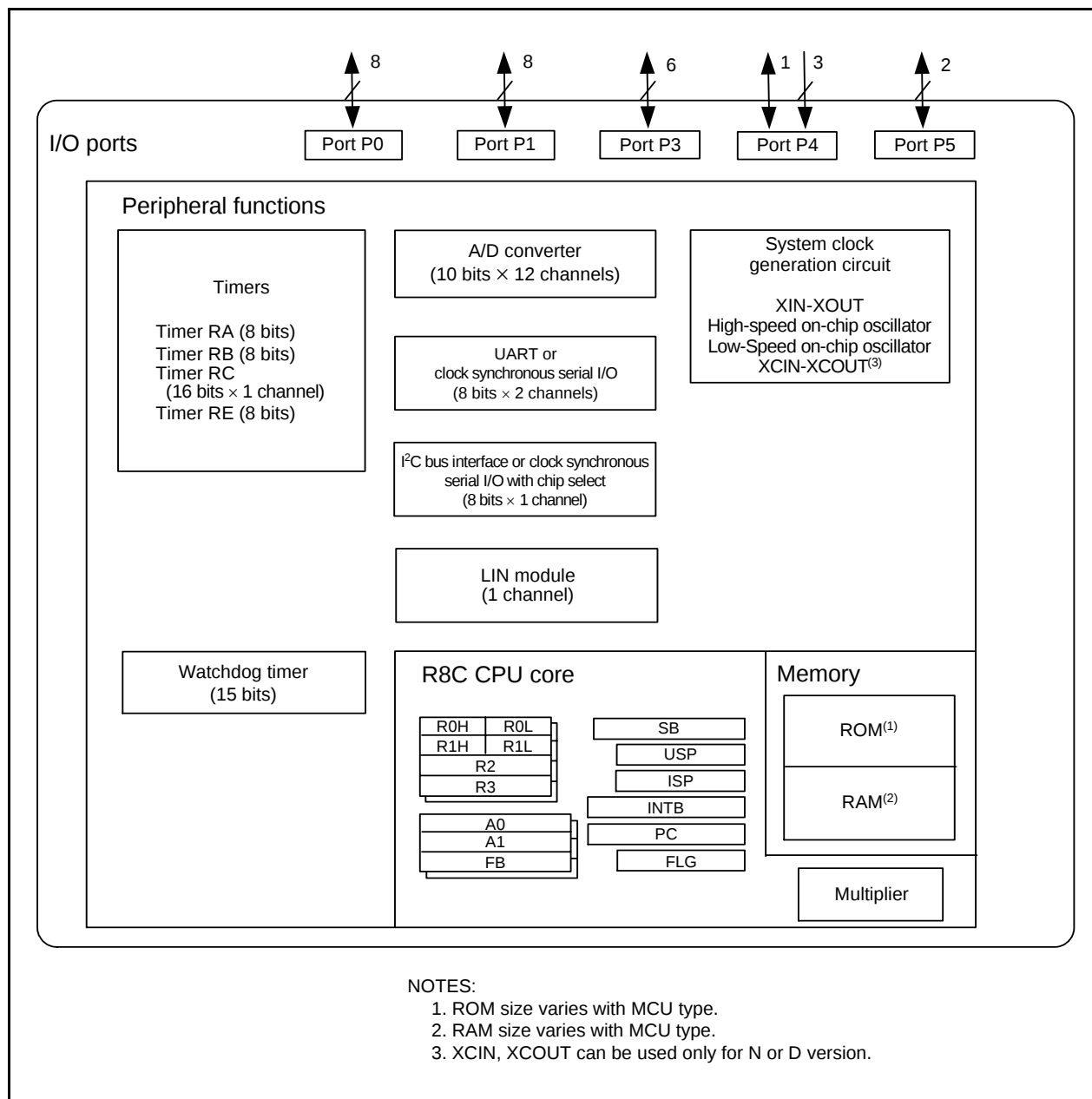


Figure 1.1 Block Diagram

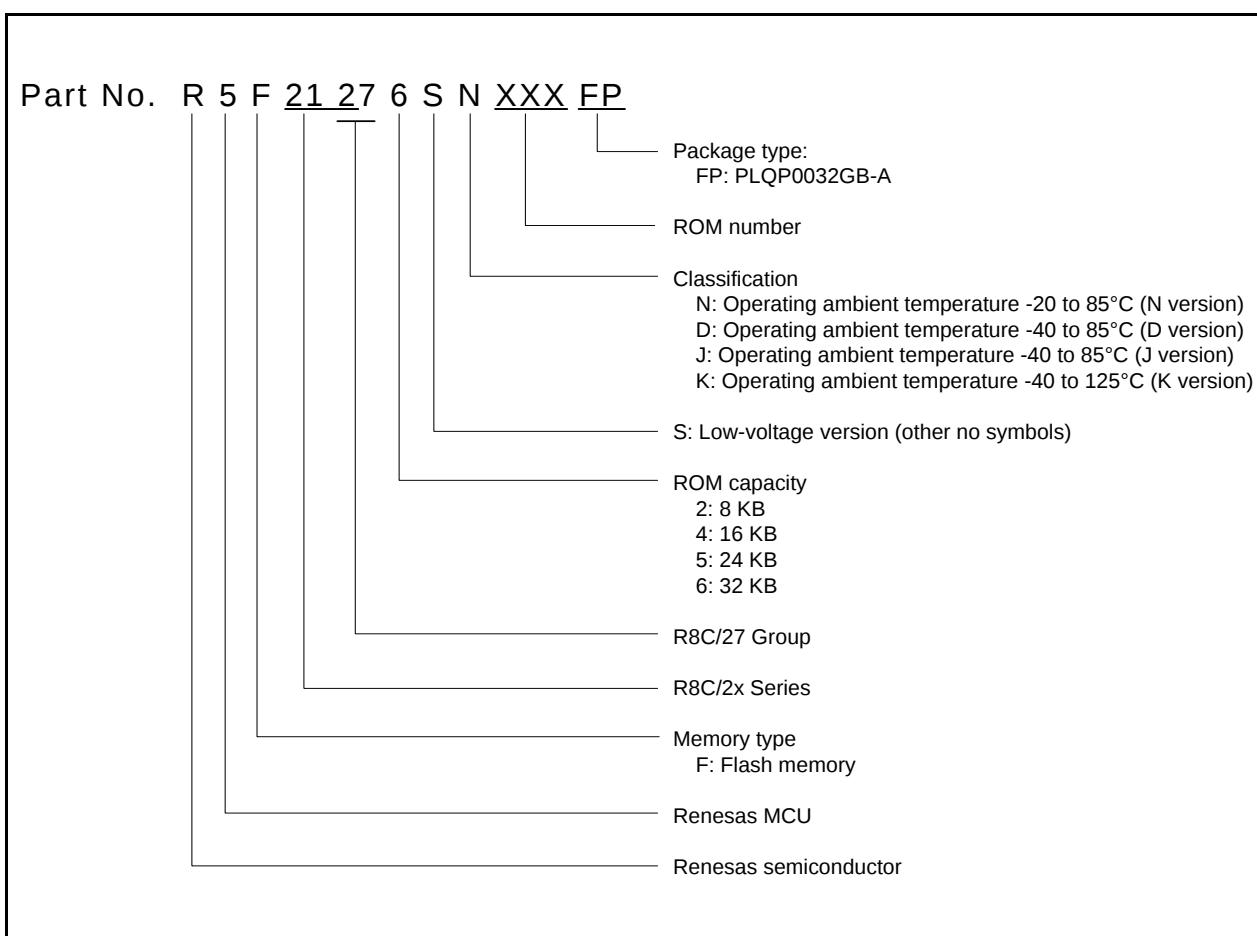


Figure 1.3 Part Number, Memory Size, and Package of R8C/27 Group

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

Table 4.2 SFR Information (2)⁽¹⁾

Address	Register	Symbol	After reset
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	• N, D version 00h⁽³⁾ 00100000b⁽⁴⁾ • J, K version 00h⁽⁷⁾ 01000000b⁽⁸⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	• N, D version 00001000b • J, K version 0000X000b⁽⁷⁾ 0100X001b⁽⁸⁾
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽⁶⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Fh			
0040h			
0041h			
0042h			
0043h			
0044h			
0045h			
0046h			
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h			
0049h			
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh			
004Ch			
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU/IIC bus Interrupt Control Register ⁽⁹⁾	SSUIC/IICIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h	UART1 Transmit Interrupt Control Register	S1TIC	XXXXX000b
0054h	UART1 Receive Interrupt Control Register	S1RIC	XXXXX000b
0055h			
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh			
005Fh			
0060h			
006Fh			
0070h			
007Fh			

X: Undefined

NOTES:

- The blank regions are reserved. Do not access locations in these regions.
- (N, D version) Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect this register.
(J, K version) Software reset, watchdog timer reset, or voltage monitor 2 reset do not affect this register.
- The LVD00N bit in the OFS register is set to 1 and hardware reset.
- Power-on reset, voltage monitor 0 reset or the LVD00N bit in the OFS register is set to 0, and hardware reset.
- (N, D version) Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect b2 and b3.
(J, K version) Software reset, watchdog timer reset, or voltage monitor 2 reset do not affect b2 and b3.
- (N, D version) Software reset, watchdog timer reset, voltage monitor 1 reset, or voltage monitor 2 reset do not affect this register.
(J, K version) These regions are reserved. Do not access locations in these regions.
- The LVD10N bit in the OFS register is set to 1 and hardware reset.
- Power-on reset, voltage monitor 1 reset, or the LVD10N bit in the OFS register is set to 0 and hardware reset.
- Selected by the IICSEL bit in the PMR register.

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	00h
00E1h	Port P1 Register	P1	00h
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h			
00E5h	Port P3 Register	P3	00h
00E6h			
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	00h
00E9h	Port P5 Register	P5	00h
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh			
00EDh			
00EEh			
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h	Pin Select Register 1	PINSR1	00h
00F6h	Pin Select Register 2	PINSR2	00h
00F7h	Pin Select Register 3	PINSR3	00h
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	00h
00FEh	Port P1 Drive Capacity Control Register ⁽²⁾	P1DRR	00h
00FFh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. In J, K version these regions are reserved. Do not access locations in these regions.

Table 4.5 SFR Information (5)⁽¹⁾

Address	Register	Symbol	After reset
0100h	Timer RA Control Register	TRACR	00h
0101h	Timer RA I/O Control Register	TRAIOC	00h
0102h	Timer RA Mode Register	TRAMR	00h
0103h	Timer RA Prescaler Register	TRAPRE	FFh
0104h	Timer RA Register	TRA	FFh
0105h			
0106h	LIN Control Register	LINCR	00h
0107h	LIN Status Register	LINST	00h
0108h	Timer RB Control Register	TRBCR	00h
0109h	Timer RB One-Shot Control Register	TRBOCR	00h
010Ah	Timer RB I/O Control Register	TRBIOC	00h
010Bh	Timer RB Mode Register	TRBMR	00h
010Ch	Timer RB Prescaler Register	TRBPRE	FFh
010Dh	Timer RB Secondary Register	TRBSC	FFh
010Eh	Timer RB Primary Register	TRBPR	FFh
010Fh			
0110h			
0111h			
0112h			
0113h			
0114h			
0115h			
0116h			
0117h			
0118h	Timer RE Second Data Register / Counter Data Register	TRESEC	00h
0119h	Timer RE Minute Data Register / Compare Data Register	TREMIN	00h
011Ah	Timer RE Hour Data Register ⁽²⁾	TREHR	00h
011Bh	Timer RE Day of Week Data Register ⁽²⁾	TREWK	00h
011Ch	Timer RE Control Register 1	TRECR1	00h
011Dh	Timer RE Control Register 2	TRECR2	00h
011Eh	Timer RE Count Source Select Register	TRECSR	00001000b
011Fh			
0120h	Timer RC Mode Register	TRCMR	01001000b
0121h	Timer RC Control Register 1	TRCCR1	00h
0122h	Timer RC Interrupt Enable Register	TRCIER	01110000b
0123h	Timer RC Status Register	TRCSR	01110000b
0124h	Timer RC I/O Control Register 0	TRCIOR0	10001000b
0125h	Timer RC I/O Control Register 1	TRCIOR1	10001000b
0126h	Timer RC Counter	TRC	00h
0127h			00h
0128h	Timer RC General Register A	TRCGRA	FFh
0129h			FFh
012Ah	Timer RC General Register B	TRCGRB	FFh
012Bh			FFh
012Ch	Timer RC General Register C	TRCGRC	FFh
012Dh			FFh
012Eh	Timer RC General Register D	TRCGRD	FFh
012Fh			FFh
0130h	Timer RC Control Register 2	TRCCR2	00011111b
0131h	Timer RC Digital Filter Function Select Register	TRCDF	00h
0132h	Timer RC Output Master Enable Register	TRCOER	01111111b
0133h			
0134h			
0135h			
0136h			
0137h			
0138h			
0139h			
013Ah			
013Bh			
013Ch			
013Dh			
013Eh			
013Fh			

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. In J, K version these regions are reserved. Do not access locations in these regions.

Table 4.7 SFR Information (7)⁽¹⁾

Address	Register	Symbol	After reset
0180h			
0181h			
0182h			
0183h			
0184h			
0185h			
0186h			
0187h			
0188h			
0189h			
018Ah			
018Bh			
018Ch			
018Dh			
018Eh			
018Fh			
0190h			
0191h			
0192h			
0193h			
0194h			
0195h			
0196h			
0197h			
0198h			
0199h			
019Ah			
019Bh			
019Ch			
019Dh			
019Eh			
019Fh			
01A0h			
01A1h			
01A2h			
01A3h			
01A4h			
01A5h			
01A6h			
01A7h			
01A8h			
01A9h			
01AAh			
01ABh			
01ACh			
01ADh			
01AEh			
01AFh			
01B0h			
01B1h			
01B2h			
01B3h	Flash Memory Control Register 4	FMR4	01000000b
01B4h			
01B5h	Flash Memory Control Register 1	FMR1	1000000Xb
01B6h			
01B7h	Flash Memory Control Register 0	FMR0	00000001b
01B8h			
01B9h			
01BAh			
01BBh			
01BCh			
01BDh			
01BEh			
01BFh			
FFFFh	Option Function Select Register	OFS	(Note 2)

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. The OFS register cannot be changed by a program. Use a flash programmer to write to it.

Table 5.3 A/D Converter Characteristics

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
—	Resolution		$V_{ref} = AV_{CC}$	—	—	10	Bits
—	Absolute accuracy	10-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 5.0 \text{ V}$	—	—	± 3	LSB
		8-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 5.0 \text{ V}$	—	—	± 2	LSB
		10-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 3.3 \text{ V}$	—	—	± 5	LSB
		8-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 3.3 \text{ V}$	—	—	± 2	LSB
		10-bit mode	$\phi_{AD} = 5 \text{ MHz}, V_{ref} = AV_{CC} = 2.2 \text{ V}$	—	—	± 5	LSB
		8-bit mode	$\phi_{AD} = 5 \text{ MHz}, V_{ref} = AV_{CC} = 2.2 \text{ V}$	—	—	± 2	LSB
R_{ladder}	Resistor ladder		$V_{ref} = AV_{CC}$	10	—	40	$k\Omega$
t_{conv}	Conversion time	10-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 5.0 \text{ V}$	3.3	—	—	μs
		8-bit mode	$\phi_{AD} = 10 \text{ MHz}, V_{ref} = AV_{CC} = 5.0 \text{ V}$	2.8	—	—	μs
V_{ref}	Reference voltage			2.2	—	AV_{CC}	V
V_{IA}	Analog input voltage ⁽²⁾			0	—	AV_{CC}	V
—	A/D operating clock frequency	Without sample and hold	$V_{ref} = AV_{CC} = 2.7 \text{ to } 5.5 \text{ V}$	0.25	—	10	MHz
		With sample and hold	$V_{ref} = AV_{CC} = 2.7 \text{ to } 5.5 \text{ V}$	1	—	10	MHz
		Without sample and hold	$V_{ref} = AV_{CC} = 2.2 \text{ to } 5.5 \text{ V}$	0.25	—	5	MHz
		With sample and hold	$V_{ref} = AV_{CC} = 2.2 \text{ to } 5.5 \text{ V}$	1	—	5	MHz

NOTES:

1. $AV_{CC} = 2.2 \text{ to } 5.5 \text{ V}$ at $T_{opr} = -20 \text{ to } 85^\circ\text{C}$ (N version) / $-40 \text{ to } 85^\circ\text{C}$ (D version), unless otherwise specified.
2. When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

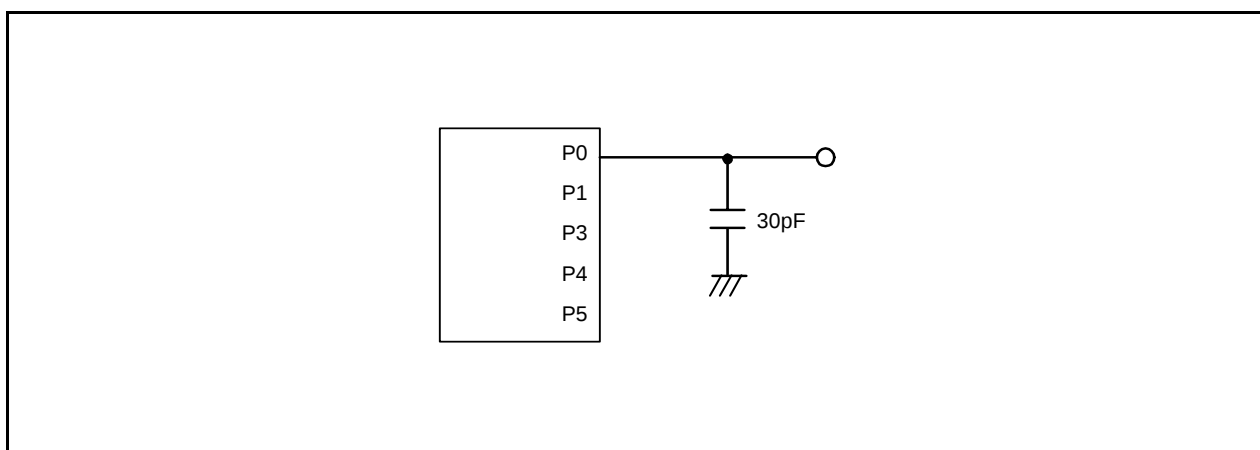
**Figure 5.1 Ports P0, P1, and P3 to P5 Timing Measurement Circuit**

Table 5.4 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾	R8C/26 Group	100 ⁽³⁾	–	–	times
		R8C/27 Group	1,000 ⁽³⁾	–	–	times
–	Byte program time		–	50	400	μs
–	Block erase time		–	0.4	9	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	97 + CPU clock × 6 cycles	μs
–	Interval from erase start/restart until following suspend request		650	–	–	μs
–	Interval from program start/restart until following suspend request		0	–	–	ns
–	Time from suspend until program/erase restart		–	–	3 + CPU clock × 4 cycles	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.2	–	5.5	V
–	Program, erase temperature		0	–	60	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55°C	20	–	–	year

NOTES:

1. V_{CC} = 2.7 to 5.5 V at T_{opr} = 0 to 60°C, unless otherwise specified.
2. Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100 or 1,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
3. Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
4. In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
5. If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
6. Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

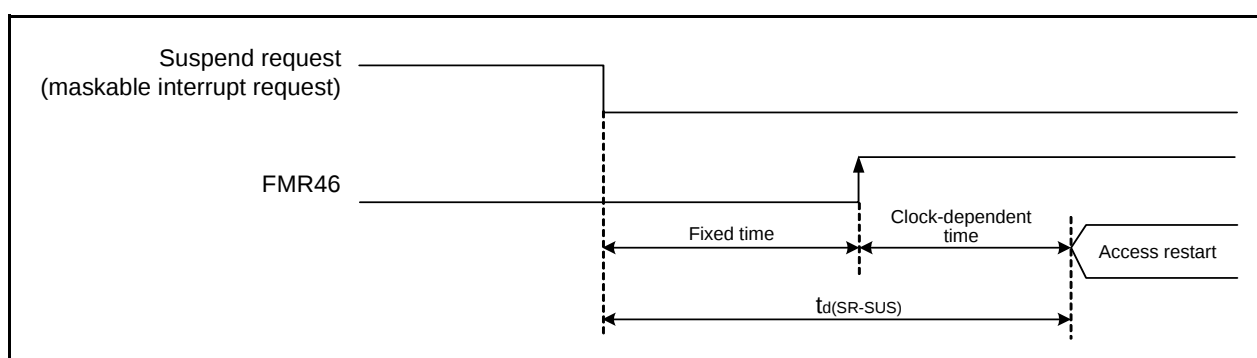


Figure 5.2 Time delay until Suspend

Table 5.6 Voltage Detection 0 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet0	Voltage detection level		2.2	2.3	2.4	V
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	0.9	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽²⁾		—	—	300	μs
Vccmin	MCU operating voltage minimum value		2.2	—	—	V

NOTES:

1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.

Table 5.7 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet1	Voltage detection level ⁽⁴⁾		2.70	2.85	3.00	V
—	Voltage monitor 1 interrupt request generation time ⁽²⁾		—	40	—	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	0.6	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

NOTES:

1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
2. Time until the voltage monitor 1 interrupt request is generated after the voltage passes Vdet1.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.
4. This parameter shows the voltage detection level when the power supply drops.
The voltage detection level when the power supply rises is higher than the voltage detection level when the power supply drops by approximately 0.1 V.

Table 5.8 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet2	Voltage detection level		3.3	3.6	3.9	V
—	Voltage monitor 2 interrupt request generation time ⁽²⁾		—	40	—	μs
—	Voltage detection circuit self power consumption	VCA27 = 1, Vcc = 5.0 V	—	0.6	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

NOTES:

1. The measurement condition is Vcc = 2.2 to 5.5 V and Topr = -20 to 85°C (N version) / -40 to 85°C (D version).
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes Vdet2.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.10 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO40M	High-speed on-chip oscillator frequency temperature • supply voltage dependence	V _{CC} = 4.75 to 5.25 V 0°C ≤ T _{opr} ≤ 60°C ⁽²⁾	39.2	40	40.8	MHz
		V _{CC} = 3.0 to 5.5 V -20°C ≤ T _{opr} ≤ 85°C ⁽²⁾	38.8	40	41.2	MHz
		V _{CC} = 3.0 to 5.5 V -40°C ≤ T _{opr} ≤ 85°C ⁽²⁾	38.4	40	41.6	MHz
		V _{CC} = 2.7 to 5.5 V -20°C ≤ T _{opr} ≤ 85°C ⁽²⁾	38	40	42	MHz
		V _{CC} = 2.7 to 5.5 V -40°C ≤ T _{opr} ≤ 85°C ⁽²⁾	37.6	40	42.4	MHz
		V _{CC} = 2.2 to 5.5 V -20°C ≤ T _{opr} ≤ 85°C ⁽³⁾	35.2	40	44.8	MHz
		V _{CC} = 2.2 to 5.5 V -40°C ≤ T _{opr} ≤ 85°C ⁽³⁾	34	40	46	MHz
		V _{CC} = 5.0 V ± 10% -20°C ≤ T _{opr} ≤ 85°C ⁽²⁾	38.8	40	40.8	MHz
		V _{CC} = 5.0 V ± 10% -40°C ≤ T _{opr} ≤ 85°C ⁽²⁾	38.4	40	40.8	MHz
		V _{CC} = 5.0 V, T _{opr} = 25°C	—	36.864	—	MHz
—	High-speed on-chip oscillator frequency when correction value in FRA7 register is written to FRA1 register ⁽⁴⁾	V _{CC} = 3.0 to 5.5 V -20°C ≤ T _{opr} ≤ 85°C	-3%	—	3%	%
—	Value in FRA1 register after reset		08h ⁽³⁾	—	F7h ⁽³⁾	—
—	Oscillation frequency adjustment unit of high- speed on-chip oscillator	Adjust FRA1 register (value after reset) to -1	—	+0.3	—	MHz
—	Oscillation stability time		—	10	100	μs
—	Self power consumption at oscillation	V _{CC} = 5.0 V, T _{opr} = 25°C	—	400	—	μA

NOTES:

1. V_{CC} = 2.2 to 5.5 V, T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.
2. These standard values show when the FRA1 register value after reset is assumed.
3. These standard values show when the corrected value of the FRA6 register is written to the FRA1 register.
4. This enables the setting errors of bit rates such as 9600 bps and 38400 bps to be 0% when the serial interface is used in UART mode.

Table 5.11 Low-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
fOCO-S	Low-speed on-chip oscillator frequency		30	125	250	kHz
—	Oscillation stability time		—	10	100	μs
—	Self power consumption at oscillation	V _{CC} = 5.0 V, T _{opr} = 25°C	—	15	—	μA

NOTE:

1. V_{CC} = 2.2 to 5.5 V, T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.

Table 5.12 Power Supply Circuit Timing Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
t _d (P-R)	Time for internal power supply stabilization during power-on ⁽²⁾		1	—	2000	μs
t _d (R-S)	STOP exit time ⁽³⁾		—	—	150	μs

NOTES:

1. The measurement condition is V_{CC} = 2.2 to 5.5 V and T_{opr} = 25°C.
2. Waiting time until the internal power supply generation circuit stabilizes during power-on.
3. Time until system clock supply starts after the interrupt is acknowledged to exit stop mode.

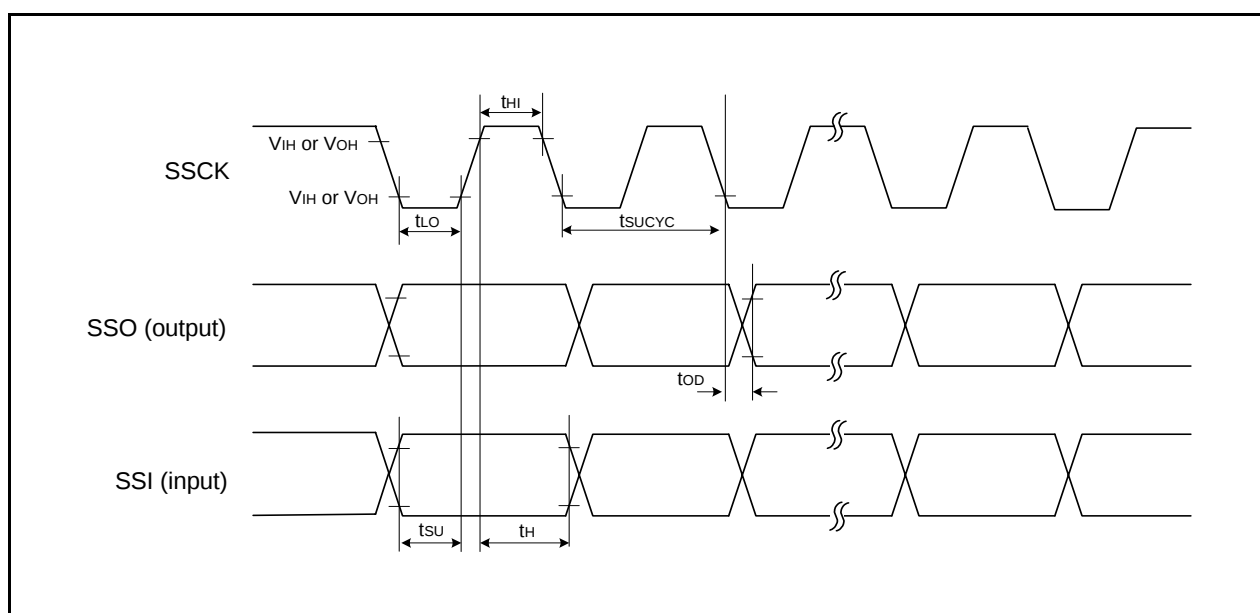


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.16 Electrical Characteristics (2) [V_{CC} = 5 V]
(T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit	
			Min.	Typ.	Max.		
I _{CC}	Power supply current (V _{CC} = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	10	17	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9	15	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	10	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	5.5	10	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	–	130	300	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	–	130	300	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	–	30	–	μA

Table 5.23 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	—	6	—	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	2	—	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	—	5	9	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	—	2	—	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	—	130	300	μA
		Low-speed clock mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz FMR47 = 1	—	130	300	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz Program operation on RAM Flash memory off, FMSTP = 1	—	30	—	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	25	70	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	23	55	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (high drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	3.8	—	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator off XCIN clock oscillator on = 32 kHz (low drive) While a WAIT instruction is executed VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	—	2.0	—	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	0.7	3.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	—	1.1	—	μA

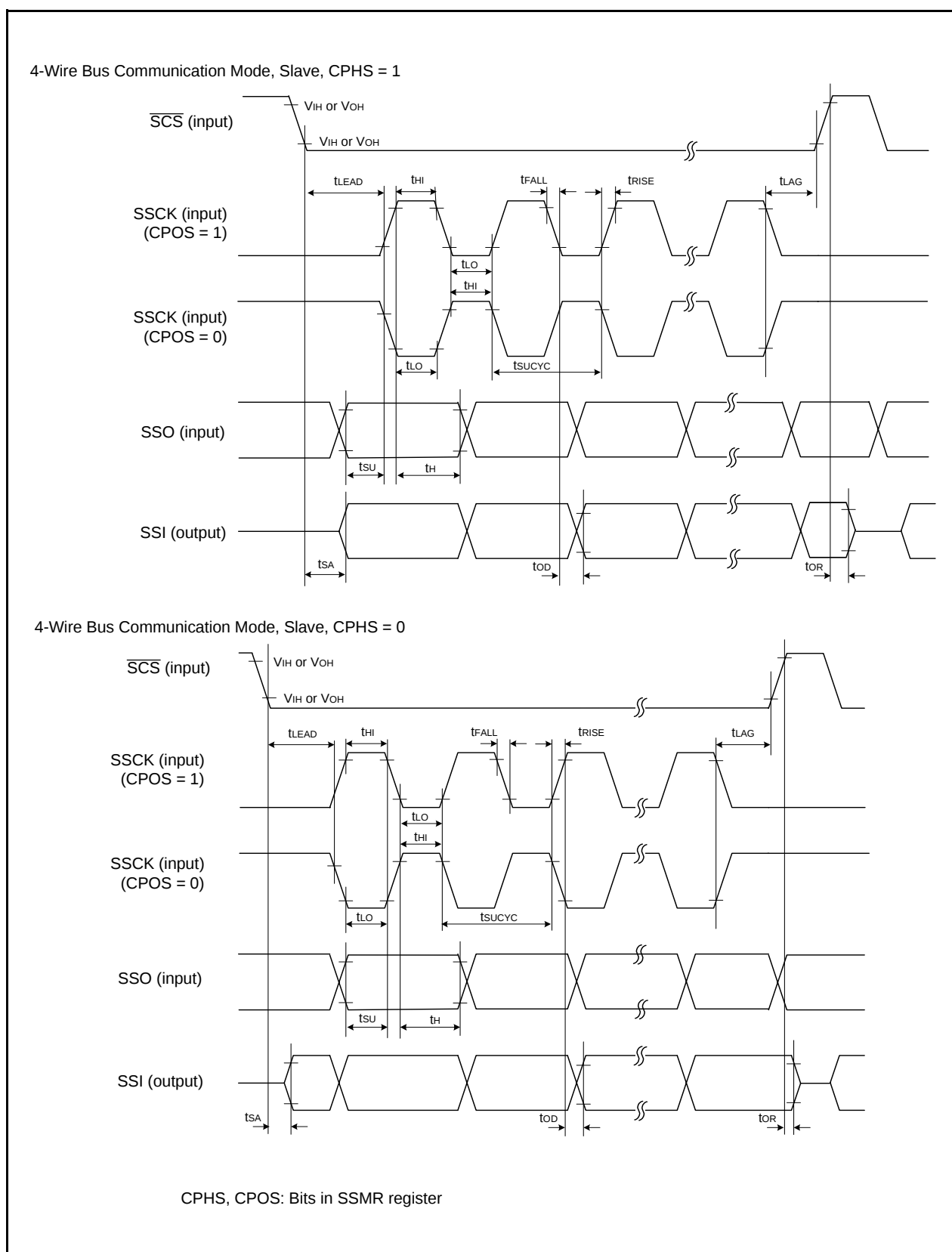


Figure 5.24 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Slave)

Table 5.47 Electrical Characteristics (1) [V_{CC} = 5 V]

Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μA	V _{CC} - 0.3	—	V _{CC}	V
		XOUT	Drive capacity HIGH I _{OH} = -1 mA	V _{CC} - 2.0	—	V _{CC}	V
			Drive capacity LOW I _{OH} = -500 μA	V _{CC} - 2.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Except XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μA	—	—	0.45	V
		XOUT	Drive capacity HIGH I _{OL} = 1 mA	—	—	2.0	V
			Drive capacity LOW I _{OL} = 500 μA	—	—	2.0	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT3}},$ KI0, KI1, KI2, KI3, TRAIO, RXD0, RXD1, CLK0, CLK1, SSI, SCL, SDA, SSO		0.1	0.5	—	V
		$\overline{\text{RESET}}$		0.1	1.0	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5V	—	—	5.0	μA
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5V	—	—	-5.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5V	30	50	167	kΩ
R _{fXIN}	Feedback resistance	XIN		—	1.0	—	MΩ
V _{RAM}	RAM hold voltage		During stop mode	2.0	—	—	V

NOTE:

1. V_{CC} = 4.2 to 5.5 V at T_{opr} = -40 to 85°C (J version) / -40 to 125°C (K version), f(XIN) = 20 MHz, unless otherwise specified.

Table 5.48 Electrical Characteristics (2) [Vcc = 5 V]
(Topr = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition		Standard			Unit
				Min.	Typ.	Max.	
Icc	Power supply current (Vcc = 3.3 to 5.5 V) Single-chip mode, output pins are open, other pins are Vss	High-speed clock mode	XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	10	17	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	9	15	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz No division	–	6	–	mA
			XIN = 20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	5	–	mA
			XIN = 16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN = 10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		High-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz (J version) Low-speed on-chip oscillator on = 125 kHz No division	–	10	15	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 20 MHz (J version) Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	4	–	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz No division	–	5.5	10	mA
			XIN clock off High-speed on-chip oscillator on fOCO = 10 MHz Low-speed on-chip oscillator on = 125 kHz Divide-by-8	–	2.5	–	mA
		Low-speed on-chip oscillator mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz Divide-by-8, FMR47 = 1	–	130	300	μA
		Wait mode	XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock operation VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	25	75	μA
			XIN clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on = 125 kHz While a WAIT instruction is executed Peripheral clock off VCA27 = VCA26 = VCA25 = 0 VCA20 = 1	–	23	60	μA
		Stop mode	XIN clock off, Topr = 25°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	0.8	3.0	μA
			XIN clock off, Topr = 85°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	1.2	–	μA
			XIN clock off, Topr = 125°C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10 = 1 Peripheral clock off VCA27 = VCA26 = VCA25 = 0	–	4.0	–	μA

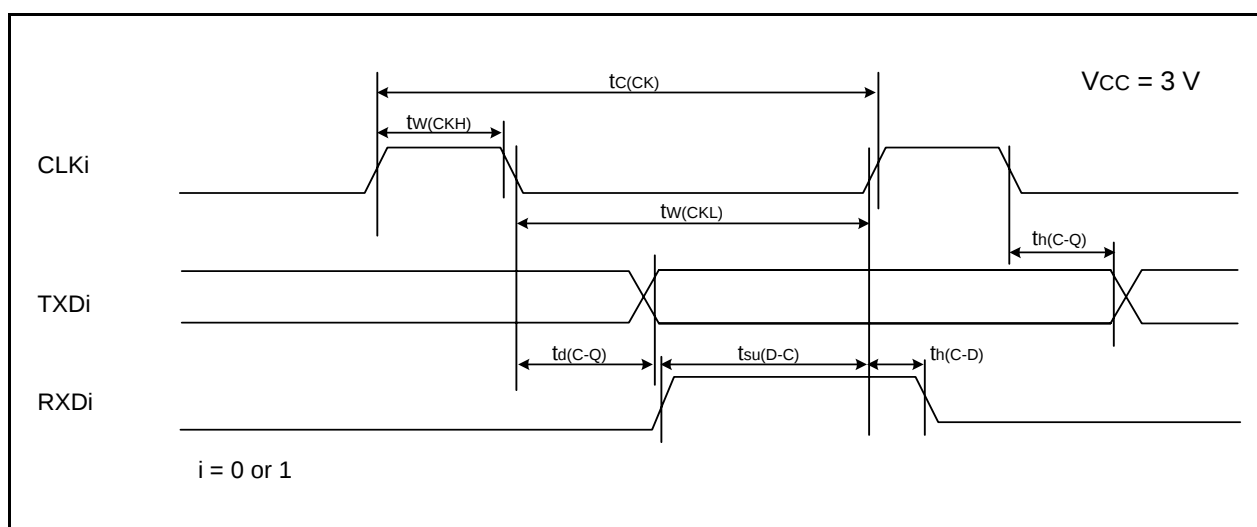
Table 5.54 Electrical Characteristics (4) [V_{CC} = 3 V]
(T_{opr} = -40 to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.)

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
I _{CC}	Power supply current (V _{CC} = 2.7 to 3.3 V) Single-chip mode, output pins are open, other pins are V _{SS}	High-speed clock mode	—	6	—	mA
		High-speed on-chip oscillator mode	—	2	—	mA
		High-speed on-chip oscillator mode	—	5	9	mA
		Low-speed on-chip oscillator mode	—	130	300	μA
		Wait mode	—	25	70	μA
		Stop mode	—	0.7	3.0	μA
		Stop mode	—	1.1	—	μA
		Stop mode	—	3.8	—	μA

Table 5.57 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	300	—	ns
$t_{w(CKH)}$	CLKi input "H" width	150	—	ns
$t_{w(CKL)}$	CLKi Input "L" width	150	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	80	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	70	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

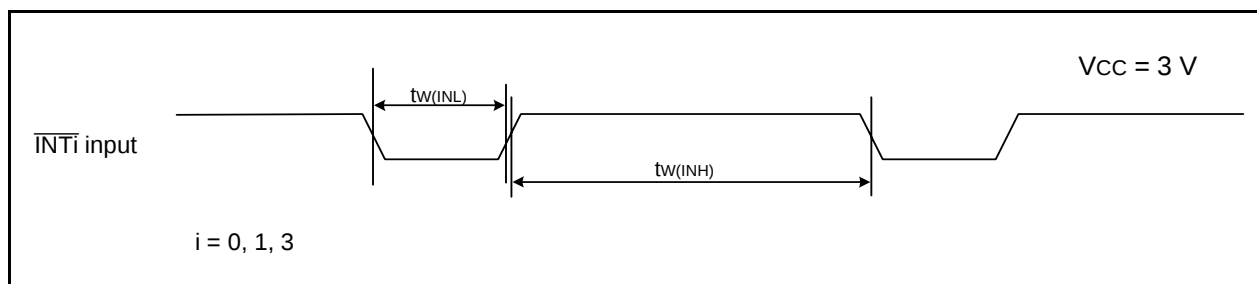
i = 0 or 1

**Figure 5.33 Serial Interface Timing Diagram when Vcc = 3 V****Table 5.58 External Interrupt $\overline{INTi}$ (i = 0, 1, 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INTi}$ input "H" width	380 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INTi}$ input "L" width	380 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

**Figure 5.34 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 3 V**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.

